







#### **Features**

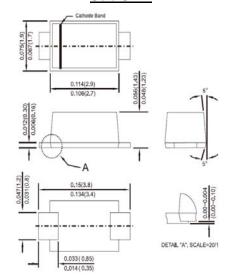
- ♦ For surface mounted application
- ♦ Glass passivated junction chip
- High temperature metallurgically bonded construction
- Plastic material used carries Underwriters Laboratory Classification 94V-0
- → High temperature soldering:
   260°C / 10 seconds at terminals
- Green compound with suffix "G" on packing code & prefix "G" on datecode

## **Mechanical Data**

- ♦ Case: Sub SMA plastic case
- ♦ Terminals: Pure tin plated, Lead free
- ♦ Polarity: Indicated by cathode band
- ♦ Packing: 8mm / 12mm tape per EIA STD RS-481
- ♦ Weight: 0.0196 grams

# 0.5AMP. Surface Mount Fast Recovery Rectifiers

## Sub SMA



### **Dimensions in inches and (millimeters)**

### **Marking Diagram**

FXL



= Specific Device Code = Green Compound

G = Green Comp Y = Year M = Work Month

## **Maximum Ratings and Electrical Characteristics**

Rating at 25  $^{\circ}$ C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

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Type Number	Symbol	RSF AL	RSF BL	RSF DL	RSF GL	RSF JL	RSF KL	RSF ML	Unit
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current .375 (9.5mm) Lead Length @ $T_L$ =55 $^{\circ}$ C	I <sub>F(AV)</sub>	0.5							Α
Peak Forward Surge Current, 8.3 ms Single Half Sinewave Superimposed on Rated Load (JEDEC method)	I <sub>FSM</sub>	10							Α
Maximum Instantaneous Forward Voltage (Note 1) @ 0.5A	V <sub>F</sub>	1.3						٧	
Maximum Reverse Current @ Rated VR $T_A$ =25 $^{\circ}$ C $T_A$ =125 $^{\circ}$ C	I <sub>R</sub>	5 50							uA
Maximum Reverse Recovery Time (Note 2)	Trr		150			250	500		nS
Typical Junction Capacitance (Note 3)	Cj	4						pF	
Typical Thermal Resistance	$R_{\theta jA} \ R_{\theta jC}$	150 32						°C/W	
Operating Temperature Range	TJ	- 55 to + 150							οС
Storage Temperature Range	T <sub>STG</sub>	- 55 to + 150							οС

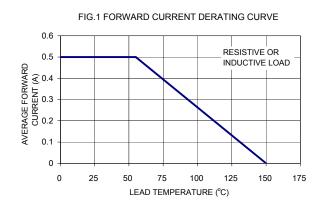
Note 1: Pulse Test with PW=300 usec, 1% Duty Cycle

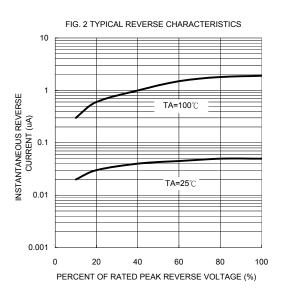
Note 2: Reverse Recovery Test Conditions:  $I_F$ =0.5A,  $I_R$ =1.0A,  $I_{RR}$ =0.25A

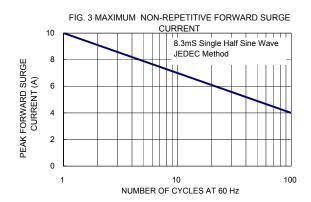
Note 3: Measured at 1 MHz and Applied Reverse Voltage of 4.0V D.C.

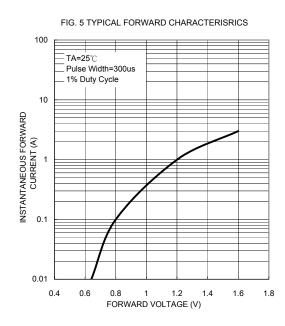


### RATINGS AND CHARACTERISTIC CURVES (RSFAL THRU RSFML)

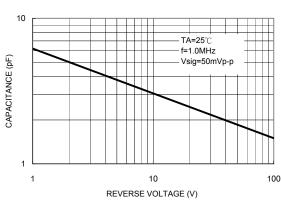












#### FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

